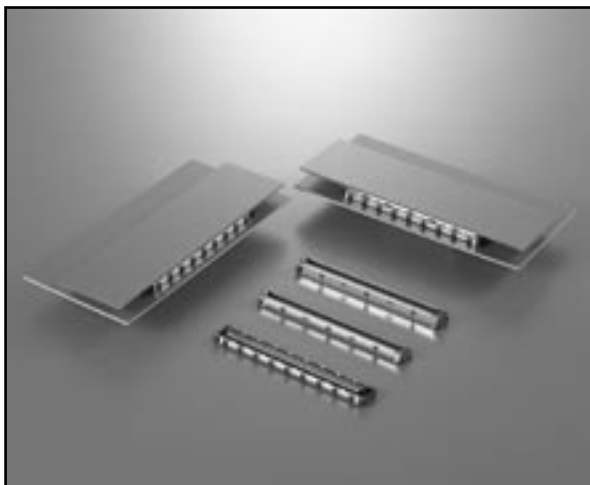


WB3 SERIES CONNECTORS

Board to Board Connector Compatible to PCI Express



FEATURES

- Compliant with PCI Express Card Electrical Mechanical SPEC
- High density 0.5mm pitch type yet having a high level transmission characteristic and high speed transmission is possible.
- Contact configuration that enables transmission of PCI Express (X16), TMDS, VGA and others.
- Parallel board to board connection is possible. Stacking height, 4mm and 5mm are available.
- EMI shielding is applied.
- Compatible to automatic mounting. Available in embossed tape package.



WB3 Series are board to board connectors satisfying the specification of the transmission characteristics of PCI Express standard. Suitable for connections between units that need TMDS transmission, such as graphic card and PCI Express.

GENERAL SPECIFICATIONS

Number of Contacts	20pos
Contact Resistance	50 milliohms max.
Dielectric Withstanding Voltage	AC250V per minute
Operating Temperature	-40°C to +85°C
Rated Current	0.5A/per pin
Mating Cycle	25 cycle
Insertion loss	-1dB min. (1.25GHz max.) -5dB min. (3.75GHz max.)
Return loss	-12dB max. (1.3GHz max.) -7dB max. (2GHz max.) -4dB (3.75GHz max.)
Cross Talk (near end)	32dB max. (1.25GHz max.) -26dB max. (3.75GHz max.)

MATERIALS AND FINISHES*

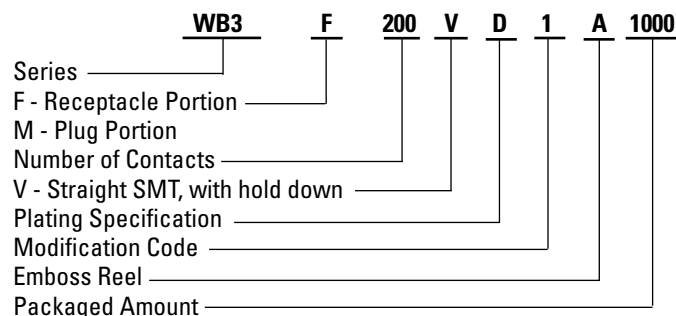
• Receptable

Description	Materials/Finishes
Contact	Copper Alloy/ Contact: 0.76um min. Au plating over Ni Terminal: Au flash plating over Ni
Insulator	Thermoplastic resin UL94V-0 black
Shell	Copper alloy: Tin plating

• Plug

Contact	Copper Alloy/ Contact: 0.76um min. Au plating over Ni Terminal: Au flash plating over Ni
Insulator	Thermoplastic resin UL94V-0 black
Shell	Stainless steel: Tin plating

ORDERING INFORMATION



• Please consult JAE for verification of product availability.

Dimensions and specifications subject to change without notice.